



## Nine-month Report

01 January – 30 September 2006



## KEY FIGURES

in Euro million	Q3/06	Q3/05	Change in %	9m/06	9m/05	Change in %
Order entry	37.5	32.3	16.1%	115.0	84.2	36.6%
Order backlog as of 09/30	–	–	–	82.8	74.7	13.4%
Total sales	31.3	27.1	15.7%	113.5	75.1	51.1%
Sales margin in %	4.3%	-5.2%	–	10.0%	-11.7%	–
Gross profit	14.0	11.9	17.9%	52.5	29.3	79.0%
Gross margin	44.7%	43.8%	–	46.2%	39.0%	–
Costs of sales	17.3	15.2	13.9%	61.0	45.8	33.3%
EBITDA	3.1	0.8	>100%	19.1	-1.7	>100%
EBITDA margin	10.0%	2.8%	–	16.8%	-2.3%	–
EBIT	1.7	-0.9	>100%	14.3	-7.0	>100%
EBIT margin	5.4%	-3.2%	–	12.6%	-9.3%	–
Earnings after tax	1.4	-1.4	>100%	11.3	-8.8	>100%
Earnings per share, diluted	0.08	-0.09	>100%	0.65	-0.57	>100%
Shareholders' equity	–	–	–	95.1	83.1	14.4%
Equity ratio	–	–	–	61.1%	50.3%	–
Return on equity	1.4%	-1.7%	–	11.9%	-10.6%	–
Balance sheet total	–	–	–	155.7	165.4	-5.9%
Net Cash	–	–	–	14.1	6.0	>100%
Free Cash Flow	5.8	3.0	89.9%	6.9	0.3	>100%
Investments	1.6	1.0	52.2%	5.2	3.4	50.5%
Investment ratio	5.0%	3.8%	–	4.6%	4.6%	–
Depreciation and amortization	1.4	1.6	-12.3%	4.8	5.2	-8.8%
Employees as of 09/30	–	–	–	741	662	11.9%



## CONTENT

Foreword by the Management Board 2

### SALES AND EARNINGS

C4NP Project – Status Quo 4

Substrate Bonder – a very good outlook 5

First-Class Service – Satisfied customers –

Testing systems extremely successful 6

Sales and Segment Figures 7

Directors' Dealings 9

### FINANCIAL REPORT

Consolidated Statement of Income and Comprehensive Income 10

Consolidated Balance Sheet 12

Consolidated Statement of Cash Flows 14

Consolidated Statement of Shareholders' Equity 16

Segment Information by Business Segment 18

Segment Information by the Region 18

Selected Explanatory Notes to the Interim Report 20



Structure of the Group

Corporate Calendar

Imprint/ Contact



+ Dr. Stefan Schneidewind, Chief Executive Officer +



+ Stephan Schulak, Chief Financial Officer +

## FOREWORD BY THE MANAGEMENT BOARD

### DEAR SHAREHOLDERS, EMPLOYEES AND BUSINESS ASSOCIATES OF SUSS MICROTEC AG,

Business development continued to be very satisfactory in the third quarter of this fiscal year as in earlier quarters. Order entry in particular was once again a very convincing factor, totaling EUR 37.5 million. The increase in order volume for the Substrate Bonder segment was a particularly welcome event, while demand for the Device Bonder also rose again in the third quarter. Order entry in the Lithography segment was on the decline compared to the previous quarters, it is nevertheless still at a very good level. From a regional perspective, the positive development in Europe and Japan are of particular note. This, among other things, also explains the growth in Substrate Bonders, since large portions of the MEMS market are settled in these two regions.

Since a unexpected high level of sales was realized in the second quarter of 2006, these shifts attracted attention in the third quarter, as was expected, with lower sales of EUR 31.3 million (Q3/2005: EUR 27.1 million). This resulted in sales of EUR 113.5 million in the first nine months of the fiscal year, compared to EUR 75.1 million during the same period the previous year.

Gross profit in the first nine months of 2006 amounted to EUR 52.5 million. The gross profit margin was increased from 39.0 percent in the first nine months of 2005 to 46.2 percent. The EBIT reached EUR 14.3 million, compared to minus EUR 7.0 million in the same period the previous year. Based on earnings after taxes of EUR 11.3 million, the earnings per share amounted to EUR 0.65.

In summary, these key figures demonstrate the stability of the gross profit margin and confirm once again the functional capability of the new cost structure and the break-even model of SUSS MicroTec.

The free cash flow developed positively during the reporting period (6.9 compared to 0.3). The reasons for this consisted mainly of the decrease in the receivables portfolio and the increase in customer down payments. Due to the large order backlog, particularly because of the positive growth dynamics in Substrate Bonders, inventory increased to EUR 64.2 million.

The Lithography segment contributed greatly to the positive business development in this quarter as well. SUSS MicroTec Coater, Mask Aligner and Developer are successful mainly in the advanced packaging and MEMS markets. In other respects, a positive trend was evident for both orders and sales in the Substrate Bonder (see also page 5) and Device Bonder segments. Information about the current state of the strategically important C4NP project can be found on page 4 of this report.

We anticipate sales of at least EUR 150 million over the entire year 2006. Based on the stable development of margins even in the third quarter, thanks most notably to the improved margin situation in Substrate Bonders, we are now assuming an EBIT margin of at least ten percent.

As you can see, we will close out fiscal year 2006 with distinctly positive results and in accordance with the projections provided earlier.

Garching, November 2006

Dr. Stefan Schneidewind  
Chief Executive Officer

Stephan Schulak  
Chief Financial Officer



▶ C4NP PROJECT – STATUS QUO

▶ SUBSTRATE BONDER – A VERY GOOD OUTLOOK

FIRST-CLASS SERVICE – SATISFIED CUSTOMERS – TESTING SYSTEMS EXTREMELY SUCCESSFUL

SALES AND SEGMENT FIGURES

DIRECTORS’ DEALINGS

### SALES AND EARNINGS

#### C4NP PROJECT – STATUS QUO

Since the inception of the C4NP Joint Development Agreement with IBM, both parties have collaborated to refine and enhance the ultimate configuration of a C4NP High Volume Manufacturing line. Technology trade offs intended to optimize process performance have been incorporated into the tool’s design and has increased both the project’s scope and delivery timeline accordingly. We are currently in discussions with IBM concerning these changes and expect our discussions to culminate in a revised agreement in 2006 . We anticipate this revision will equitably reflect the significant change in scope and efforts of this project.

Among the most important of the changes in our agreement is the approach to releasing the product. Current plans now anticipate the initial release of a semi-automated tool set in 2006 which will be expanded to more functional, fully automated manufacturing line in Q2 2007.

We continue to expect orders from other customers in 2007 and see high interest in the technology from broad segments of the industry. We remain confident that as soon as the high volume manufacturing process is established that C4NP, with its unique flexibility in handling conventional solders, lead free solders, tertiary and re-enforced solders, and other novel bumping materials over a very wide range of applications will enjoy the potential to gain a significant share of the wafer bumping market.

#### SUBSTRATE BONDER – A VERY GOOD OUTLOOK

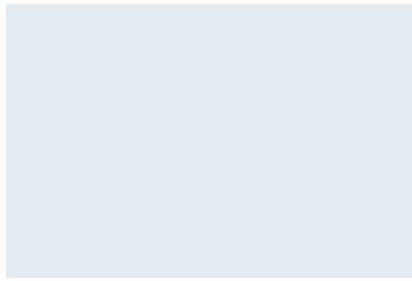
The Substrate (or Wafer) Bonder segment is developing very well with much success anticipated. Wafer Bonders are used in the MEMS market. Examples of end products include sensors for airbags, GPS systems, tire pressure, parking assistance, rain sensors and stability systems in cameras, cell phones and mobile game consoles. In addition to these, there are many other applications for use in microsystems, such as rear projection video projectors (beamers), inkjet print heads and biochips. In the manufacture of these sensors, SUSS MicroTec Wafer Bonders are utilized in mass production.

In the Wafer Bonding process, one option is that two wafers are aligned to each other very precisely and then “bonded” to each other. This process is required in the production of microsystems, in order to produce hollow spaces in which mechanical parts can move. The other option is to align a processed wafer to a glass plate and then “bond” it to the plate. In this case, the glass plate serves as a type of cover for the microsystem.

Wafer Bonders from SUSS MicroTec are also used in leading research and development institutes. Customers such as Nanoworld and Micralyne are technology leaders in microsystems technology. With customers such as these, SUSS MicroTec keeps in tune with the market and thus has an opportunity to play a role in the future of Wafer Bonding. Through close collaboration with these research and development institutes, we learn about the future needs of our production customers and how to satisfy them.

The new M-Lock Wafer Bonder, introduced at the SEMICON West trade show in July, was developed with these factors in mind. The special feature of this device is a vacuum lock that removes as many of the contaminations as possible from the wafers to be processed. This is extremely





C4NP PROJECT – STATUS QUO

SUBSTRATE BONDER – A VERY  
GOOD OUTLOOK▶ FIRST-CLASS SERVICE – SATISFIED  
CUSTOMERS – TESTING SYSTEMS  
EXTREMELY SUCCESSFUL

▶ SALES AND SEGMENT FIGURES

DIRECTORS' DEALINGS

important in microsystems production, since every impurity reduces the production yield. Production devices must therefore achieve the highest possible yields. The state-of-the-art M-Lock wafer bonder was accepted by our customers with equal enthusiasm. SUSS MicroTec is expecting a significant increase in business volume in this segment over the next several years.

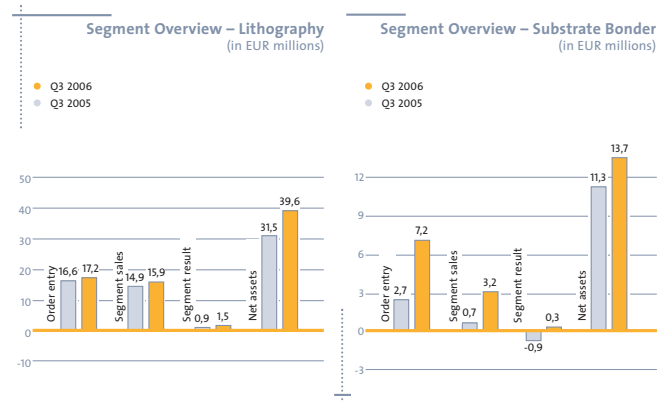
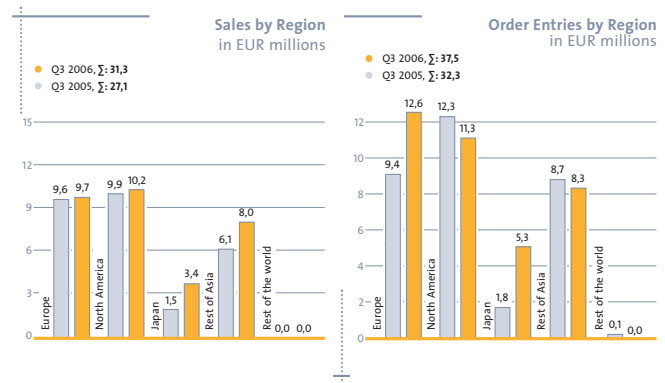
#### FIRST-CLASS SERVICE – SATISFIED CUSTOMERS – TESTING SYSTEMS EXTREMELY SUCCESSFUL

Satisfied customers are essential for success in the market. Each year, VLSI Research Inc. conducts a survey in the semiconductor industry. The answers to the survey then determine the equipment suppliers with the greatest customer satisfaction in various categories.

SUSS has been among the winners for many years now. The same is true again this year, with an outstanding first place in the “Material Handling Equipment” category and seventh place in the “Best Wafer Processing Equipment – Small Suppliers” category.

The “Material Handling Equipment” category primarily includes SUSS MicroTec’s test and measurement systems. This segment introduced a new product to the market during the summer: the Blue-Ray Probe System, a wafer prober that can test up to 70,000 chips per hour. This speed is particularly important when testing LEDs and offers cost advantages in that there are tens of thousands of LEDs on a single wafer. Another special feature of the Blue-Ray Probe System is that it can be set up for customers who have a semi-automatic or a fully automatic system. In this way, the device can “grow along with” the production needs of our customers. This makes it extremely efficient and attractive – particularly for our Asian customers.

#### SALES AND SEGMENT FIGURES



C4NP PROJECT – STATUS QUO

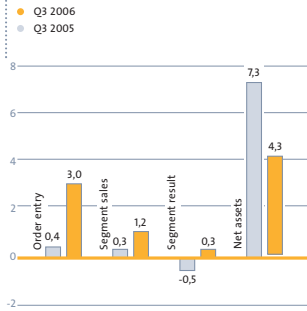
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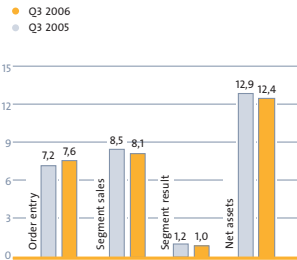
► SALES AND SEGMENT FIGURES

► DIRECTORS' DEALINGS

Segment Overview – Device Bonder  
(in EUR millions)



Segment Overview – Test Systems  
(in EUR millions)

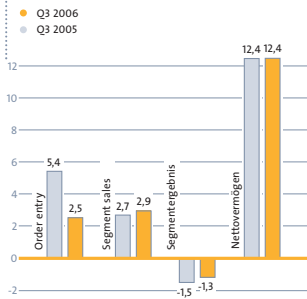


### DIRECTORS' DEALINGS AS OF 09/30/2006

Management Board:	Options	Shares
Dr. Stefan Schneidewind	109,648	6,571
Stephan Schulak	120,286	13,000

Supervisory Board:	Shares
Dr. Winfried Süs	1,131,000
Gerhard Rauter	–
Dr. e. h. Horst Görtz	17,216
Peter Heinz	1,338
Prof. Dr. Anton Heuberger	–
Dr. Christoph Schücking	500

Segment Overview of Others Segment  
(in EUR millions)



▶ STATEMENT OF INCOME\*

BALANCE SHEET\*

STATEMENT OF CASH FLOWS\*

STATEMENT OF

SHAREHOLDERS' EQUITY\*

SEGMENT REPORTING\*

NOTES\*

## FINANCIAL REPORT

## IFRS – CONSOLIDATED STATEMENT OF INCOME

TEUR	07/01/06 – 09/30/06	07/01/05 – 09/30/05	01/01/06 – 09/30/06	01/01/05 – 09/30/05
Sales	31,340	27,093	113,458	75,073
Cost of sales	-17,328	-15,213	-60,991	-45,765
<b>Gross profit</b>	<b>14,012</b>	<b>11,880</b>	<b>52,467</b>	<b>29,308</b>
Selling costs	-5,402	-5,787	-17,317	-16,618
Research and development costs	-1,179	-2,199	-4,783	-5,926
Administration costs	-5,397	-5,039	-15,167	-15,988
Other operating income	605	652	1,491	3,225
Other operating expenses	-938	-377	-2,416	-957
Result from at-equity investments	0	0	0	-22
<b>Analysis of net income from operations (EBIT):</b>				
EBITDA (Earnings before Interest and Taxes, Depreciation and Amortization)	3,126	755	19,061	-1,731
Depreciation and amortization of tangible assets, intangible assets and investments in subsidiaries	-1,425	-1,625	-4,786	-5,247
<b>Net income from operations (EBIT)</b>	<b>1,701</b>	<b>-870</b>	<b>14,275</b>	<b>-6,978</b>
Interest expenses	-154	-465	-712	-1,466
Interest income	108	73	348	398
<b>Income before taxes</b>	<b>1,655</b>	<b>-1,262</b>	<b>13,911</b>	<b>-8,046</b>
Income taxes	-305	-158	-2,601	-758
<b>Net profit or loss</b>	<b>1,350</b>	<b>-1,420</b>	<b>11,310</b>	<b>-8,804</b>
Thereof minority interests	52	6	94	-15
Thereof equity holders of SUSS MicroTec	1,298	-1,426	11,216	-8,789
<b>Earnings per share</b>				
Basic earnings per share in EUR	0.08	-0.09	0.67	-0.57
Diluted earnings per share in EUR	0.08	-0.09	0.65	-0.57

STATEMENT OF INCOME\*

▶ BALANCE SHEET\*

STATEMENT OF CASH FLOWS\*

STATEMENT OF

SHAREHOLDERS' EQUITY\*

SEGMENT REPORTING\*

NOTES\*

## IFRS – CONSOLIDATED BALANCE SHEET

TEUR ASSETS	09/30/06	12/31/05
<b>Non-current assets</b>	<b>50,394</b>	<b>50,401</b>
Intangible assets	14,000	13,668
Goodwill	23,023	23,560
Tangible assets	5,117	5,384
Other investments	5	33
Other assets	332	364
Deferred tax assets	7,917	7,392
<b>Current assets</b>	<b>105,337</b>	<b>106,920</b>
Inventories	64,184	53,837
Accounts receivable	16,477	23,681
Securities	20	58
Tax assets	1,734	1,120
Cash and cash equivalents	20,892	26,325
Other assets	2,030	1,899
<b>Total assets</b>	<b>155,731</b>	<b>157,321</b>

TEUR LIABILITIES & SHAREHOLDERS' EQUITY	09/30/06	12/31/05
<b>Shareholders' equity</b>	<b>95,082</b>	<b>84,165</b>
Subscribed capital	16,804	16,793
Reserves	78,120	66,640
Accumulated other comprehensive income	15	683
Minority interests	143	49
<b>Non-current liabilities</b>	<b>11,695</b>	<b>13,800</b>
Pension provisions	2,670	2,581
Other provisions	365	455
Financial debt	3,442	5,957
Other liabilities	245	245
Deferred tax liabilities	4,973	4,562
<b>Current liabilities</b>	<b>48,954</b>	<b>59,356</b>
Other provisions	4,340	3,968
Tax liabilities	2,254	394
Financial debt	3,331	12,832
Accounts payable	6,229	6,061
Other liabilities	32,800	36,101
<b>Total liabilities &amp; shareholders' equity</b>	<b>155,731</b>	<b>157,321</b>



STATEMENT OF INCOME\*

BALANCE SHEET\*

▶ STATEMENT OF CASH FLOWS

STATEMENT OF

SHAREHOLDERS' EQUITY

SEGMENT REPORTING\*

NOTES\*

## IFRS – CONSOLIDATED STATEMENT OF CASH FLOWS

TEUR	01/01/06 – 09/30/06	01/01/05 – 09/30/05
Net profit or loss	11,310	-8,804
Amortization of intangible assets	3,023	2,934
Depreciation of tangible assets	1,763	2,313
Change of at-equity measured associates	0	22
Profit or loss on disposal of intangible and tangible assets	2	3
Change of reserves on inventories	1,619	99
Change of reserves for bad debts	391	129
Non-cash stock based compensation	263	363
Non-cash income from the reversal of provisions	-199	-1,015
Non-cash interest expenses from increase of convertible debt	81	366
Other non-cash effective income and expenses	1,686	-1,607
Change in inventories	-14,031	-1,168
Change in accounts receivable	5,993	11,327
Change in other assets	-713	-408
Change in pension provisions	89	-36
Change in accounts payable	909	-2,435
Change in other liabilities and other provisions	24	1,320
Change of deferred taxes	-114	302
<b>Cash Flow from operating activities</b>	<b>12,096</b>	<b>3,705</b>

TEUR	01/01/06 – 09/30/06	01/01/05 – 09/30/05
Payments in tangible assets	-1,668	-1,497
Payments in intangible assets	-3,508	-1,943
<b>Cash Flow from investing activities</b>	<b>-5,176</b>	<b>-3,440</b>
Increase of bank loans	478	1,250
Repayment of bank loans	-7,150	-2,077
Repayment of convertible bond	-3,622	0
Change of current bank liabilities	-1,691	930
Change in other financial debt	-54	317
Proceeds from share capital contribution	0	6,844
Payments for expenses related to capital contribution	0	-109
Proceeds from issuance of common stocks	12	148
<b>Cash Flow from financing activities</b>	<b>-12,027</b>	<b>7,303</b>
Adjustments to funds caused by exchange-rate fluctuations	-326	412
<b>Change in cash and cash equivalents</b>	<b>-5,433</b>	<b>7,980</b>
Funds at beginning of the year	26,325	22,534
<b>Funds at end of the period</b>	<b>20,892</b>	<b>30,514</b>
Cash flow from operating activities includes:		
Interest paid during the period	579	951
Interest received during period	348	398
Tax paid during the period	894	213
Tax refunds during the period	35	403

STATEMENT OF INCOME

BALANCE SHEET

STATEMENT OF CASH FLOWS

▶ STATEMENT OF  
SHAREHOLDERS' EQUITY

SEGMENT REPORTING

NOTES

## IFRS – CONSOLIDATED STATEMENT OF SHAREHOLDERS' EQUITY

TEUR	Number of shares (in thousands)	Subscribed capital	Additional paid-in capital	Earnings reserve	Retained Earnings	Accumulated other comprehensive income	Minority interests	Total
<b>As of 01 January 2005</b>	<b>15,157</b>	<b>15,157</b>	<b>84,917</b>	<b>433</b>	<b>-16,233</b>	<b>-902</b>	<b>44</b>	<b>83,416</b>
Proceeds from share capital contribution	1,456	1,456	5,388					6,844
Expenses related to share capital contribution, net of tax			-109					-109
Issuance of shares:								
Exercise of stock options	134	134	14					148
Issuance of subscription rights			363					363
Net profit loss or loss					-8,789		-15	-8,804
Foreign currency adjustment						1,275		1,275
<b>As of 30 September 2005</b>	<b>16,747</b>	<b>16,747</b>	<b>90,573</b>	<b>433</b>	<b>-25,022</b>	<b>373</b>	<b>29</b>	<b>83,133</b>
<b>As of 01 January 2006</b>	<b>16,793</b>	<b>16,793</b>	<b>90,673</b>	<b>433</b>	<b>-24,466</b>	<b>683</b>	<b>49</b>	<b>84,165</b>
Issuance of shares:								
Exercise of stock options	11	11	1					12
Issuance of subscription rights			263					263
Net profit loss or loss					11,216		94	11,310
Unrealized loss from securities net of tax						-24		-24
Foreign currency adjustment						-644		-644
<b>As of 30 September 2006</b>	<b>16,804</b>	<b>16,804</b>	<b>90,937</b>	<b>433</b>	<b>-13,250</b>	<b>15</b>	<b>143</b>	<b>95,082</b>



STATEMENT OF INCOME\*

BALANCE SHEET\*

STATEMENT OF CASH FLOWS\*

STATEMENT OF  
SHAREHOLDERS' EQUITY\*

▶ SEGMENT REPORTING

NOTES\*

## IFRS – SEGMENT REPORTING

## SEGMENT INFORMATION BY BUSINESS SEGMENT

TEUR	Lithography		Substrate Bonder		Device Bonder		Test Systems		Other		Total	
	1/1–9/30 2006	1/1–9/30 2005	1/1–9/30 2006	1/1–9/30 2005	1/1–9/30 2006	1/1–9/30 2005	1/1–9/30 2006	1/1–9/30 2005	1/1–9/30 2006	1/1–9/30 2005	1/1–9/30 2006	1/1–9/30 2005
Sales	67,544	41,010	11,787	3,644	4,019	3,623	20,714	19,917	9,394	6,879	113,458	75,073
Result per segment	15,158	-2,129	192	-3,076	724	-430	1,911	804	-2,799	-3,408	15,186	-8,239
Result from equity method accounting	0	-22	0	0	0	0	0	0	0	0	0	-22
Significant non-cash items	-1,417	689	-54	-220	-461	132	43	-490	-185	313	-2,074	424
Segment assets	64,416	64,302	17,467	14,569	7,340	8,595	16,981	18,619	16,597	13,407	122,801	119,492
thereof Goodwill	13,599	13,599	0	0	0	1,839	4,416	4,548	5,008	5,262	23,023	25,248
Segment liabilities	-24,853	-32,802	-3,815	-3,265	-3,032	-1,266	-4,627	-5,744	-4,165	-986	-40,492	-44,063
Depreciation and amortisation	2,459	2,672	808	634	140	134	235	344	1,144	1,463	4,786	5,247
thereof scheduled	2,299	2,194	808	634	140	134	235	344	1,144	1,463	4,626	4,769
thereof impairment loss	160	478	0	0	0	0	0	0	0	0	160	478
Capital expenditure	1,408	803	925	397	39	25	177	186	2,627	2,029	5,176	3,440
Average workforce during the year	299	263	89	75	45	41	130	127	178	156	741	662

## SEGMENT INFORMATION BY REGION

TEUR	Sales		Capital expenditure		Assets	
	1/1–30/9 2006	1/1–30/9 2005	1/1–30/9 2006	1/1–30/9 2005	1/1–30/9 2006	1/1–30/9 2005
Europe	31,367	26,299	3,042	1,524	76,851	83,800
North-America	37,029	29,884	1,888	1,289	43,064	35,142
Japan	11,066	5,306	49	12	6,106	2,120
Rest of Asia	33,717	13,555	51	28	630	588
Rest of world	279	29	146	587	3,666	3,359
Consolidation effects	0	0	0	0	-7,516	-5,517
<b>Total</b>	<b>113,458</b>	<b>75,073</b>	<b>5,176</b>	<b>3,440</b>	<b>122,801</b>	<b>119,492</b>

## SELECTED EXPLANATORY NOTES TO THE INTERIM REPORT OF SUSS MICROTEC AG AS OF SEPTEMBER 30, 2006

### 1. GENERAL ACCOUNTING POLICIES

The consolidated financial statements of SUSS MicroTec AG as of December 31, 2005 were prepared in accordance with International Financial Reporting Standards (IFRSs) issued by the International Accounting Standards Board (IASB) and valid as of the balance sheet date. The interim Group financial statements as of September 30, 2006, which have been prepared in accordance with International Accounting Standard (IAS) 34 “Interim Financial Reporting”, have been drawn up using the same accounting methods as in the 2005 Group financial statements.

All interpretations of the International Financial Reporting Interpretations Committee (IFRIC), which are mandatory as of September 30, 2006 have also been applied.

For additional information on the individual accounting methods applied, please refer to the consolidated financial statements of SUSS MicroTec AG as of December 31, 2005.

The interim financial statements were neither audited by the group's auditors, KPMG Deutsche Treuhand-Gesellschaft, Aktiengesellschaft, Wirtschaftsprüfungsgesellschaft, nor did they undergo an auditing review.

All amounts are indicated in thousands of euros (EUR '000) unless otherwise noted.

### 2. CHANGES IN THE GROUP STRUCTURE

The financial statements of SUSS MicroTec AG and all of the major companies for which there is a group control option according to the control principle, irrespective of the level of participating interest, are included in the consolidated financial statements.

The consolidated financial statements include the accounts of SUSS MicroTec REMAN GmbH for the first time. SÜSS MicroTec AG has a 100 per cent stake in this company. The object of SUSS MicroTec REMAN GmbH is to operate the used equipment business of the business segment “Lithography”. The changes in the composition of the Group do not have a material impact on the earnings performance, financial position and net assets of the Group.

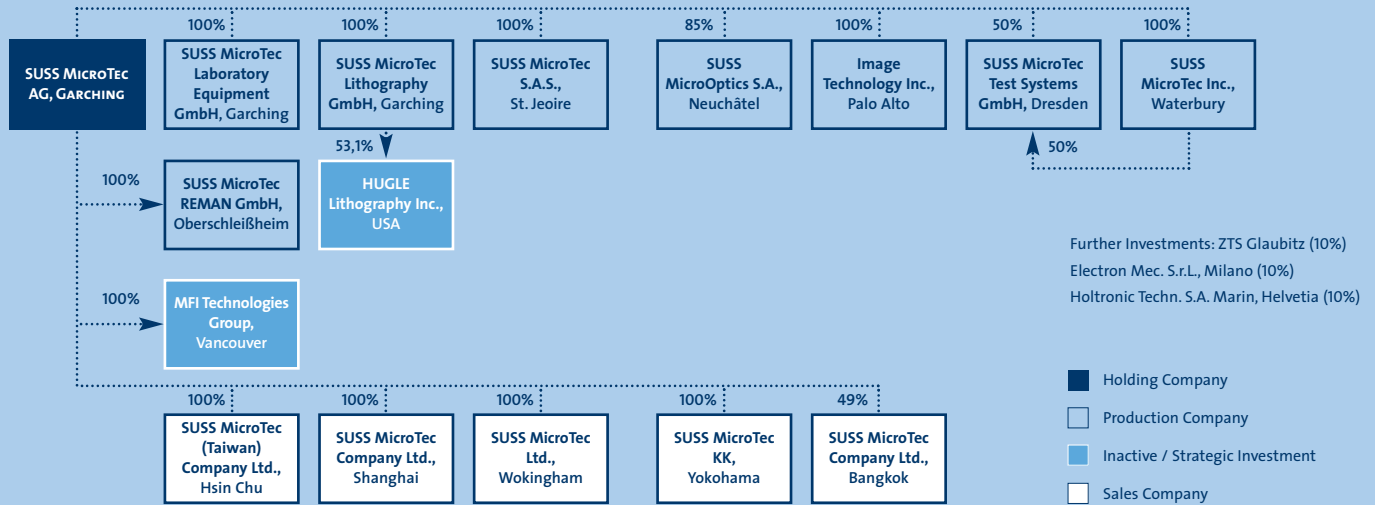
Apart from that, the group reporting entity is unchanged from the end of the financial year 2005.

### 3. FACTS SUBJECT TO REPORTING REQUIREMENTS

There were no circumstances during the interim reporting period which had any impact on the assets, liabilities, shareholders' equity, period results or cash flow and which were unusual due to their type, extent or frequency.



## Structure of the Group



## CORPORATE CALENDAR

Micromachine 2006	November 7 – 9	Tokyo, Japan
SEMICON Japan	December 6 – 8	Chiba, Japan

## IMPRINT

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**Forward-looking statements:** The reports contain forward-looking statements. Statements that are not historical facts, including statements about our beliefs and expectations, are forward-looking statements. These statements are based on current plans, estimates and projections, and you should not place too much reliance on them. Forward-looking statements speak only as of the date they are

made, and we undertake no obligation to update any of them in light of new information or future events. Forward-looking statements involve inherent risks and uncertainties. We caution you that a number of important factors could cause actual results or outcomes to differ materially from those expressed in any forward-looking statement.



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